

Overvoltage protection reference design



Product summary STDES-OVP001

Product summary			
SCR1	TN1605H-8T		
SCR2	TN5015H-8T		
TVS1	P6KE440A		
TVS2	P6KE300A/ P6KE350A		

Features

- Up to 6 kV surge protection in differential mode between line and neutral
- Compliant with IEC61000-4-5
- 3 different configurations to fit application requirements of:
 - Surge level: up to 6 kV
 - Line voltage : up to 400 V AC
 - DC/DC MOSFET V_{(BR)DSS} ratings
- High Temperature Thyristors SCRs with I_{PP} 8/20 µs during surge:
 - TN1605H-8T up to 1100 A
 - TN5015H-8T up to 1800 A
- Very low leakage current: max. 210 nA according to board configuration at AC input voltage 400 V
- SCRs Thyristors are halogen-free and lead-free plating
 - ECOPACK2 power package

Applications

- Server and telecom SMPS
- Consumer SMPS
- EV chargers
- UPS

Description

The STDES-OVP001 is a plug-and-play demonstration kit to perform IEC61000-4-5 test in SMPS, EV charger or UPS.

The SCR-based solution proposed is able to reach high level of surge voltage up to 6 kV, to protect the DC/DC of the system without any failure, especially to protect high voltage 650 V or 800 V of V_{DSS} MOSFET.

The kit is split into four different configurations, to reach high performance of protection according to the application requirements.

SCR Thyristors TN1605H-8T and TN5015H-8T are two high temperature 800V devices used in the versions of board STDES-OVP001, in the TO-220-AB package. It is environmentally friendly ECOPACK2, RoHS (2011/65/EU) and Halogen Free compliant.

The TO-220-AB package is also UL-94, V0 flammability resin compliance and RoHS (2011/65/EU) compliant



1 Getting started

Figure 1. Pictograms



Danger:

Use the STDES-OVP001 board only after applying a fire-resistant cover. The cover is not included in the board package.

There is a danger of serious personal injury, property damage, or death due to electrical shock and burn hazards if the kit or components are improperly used or installed incorrectly.

Warning:

The kit is not electrically isolated from the high-voltage supply AC-DC input.

The evaluation board is directly linked to the mains voltage. No insulation is ensured between the accessible parts and the high voltage. All measurement equipment must be isolated from the mains before powering the board.

When using an oscilloscope with the evaluation board, it must be isolated from the AC line. This prevents shock from occurring as a result of touching any single point in the circuit, but does no prevent shock when touching two or more points in the circuit.

Caution:

During assembly, testing, and operation, the evaluation board poses several inherent hazards, including bare wires, moving or rotating parts and hot surfaces. All operations involving transportation, installation, use, and maintenance must be performed by skilled technical personnel who are familiar with the installation, use, and maintenance of power electronic systems.

The board has to be connected directly on the mains. Non-isolated parts at high-voltage levels are present on both sides of the PCB.

The high current flowing through the SCR generate heat: the board temperature can reach up to 150 °C at full power. Be aware that, due to the thermal inertia, the board could remain hot even after the current flow.

Workarea safety:

- The work area must be clean and tidy
- Do not work alone when boards are powered
- Protect the area against any unauthorized access by putting suitable barriers and signs
- A system architecture that supplies power to the evaluation board must be equipped with additional
 control and protective devices in accordance with the applicable safety requirements (that is, compliance
 with technical equipment and accident prevention rules).

Electrical safety:

- Remove the power supply from the evaluation board and electrical loads before performing any electrical measurement
- Arrange measurement setup, wiring, and configuration, paying attention to the high voltage section
- Once the setup is complete, power the board. Fuse protection is not included with this evaluation board.

Danger:

Do not touch the evaluation board when it is powered or immediately after it has been disconnected from the voltage supply as several parts and power terminals containing potentially energized capacitors need time to discharge, and heat-sink and transformers may still be very hot.

Personal safety:

- Always wear suitable personal protective equipment, such as insulating gloves and safety glasses
- Take adequate precautions and install the board to prevent accidental touch
- Use protective shields, such as an insulating box with interlocks.

DB5116 - Rev 2 page 2/11



2 BOM

Table 1. STDES-OVP001 Bill of materials

Product	V1	V2 V3		V4
SCR	TN1605H-8T	TN5015H-8T	TN5015H-8T	TN5015H-8T
TVS	P6KE440A	P6KE440A	P6KE440A	P6KE350A / P6KE300A
MOV	S14K250	S14K150	S14K130	S14K175
R _G	10 Ω	10 Ω	10 Ω	10 Ω
R1	10 kΩ	10 kΩ	10 kΩ	10 kΩ
Rectifier bridge	(Optional: in case the board is plugged in AC line side)			

DB5116 - Rev 2 page 3/11



3 Schematics

Figure 2. Schematics of STDES-OVP001

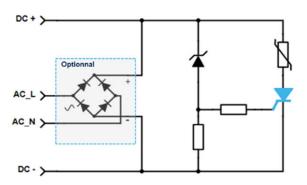


Figure 3. Implementation of the STDES-OVP001 on an SMPS before rectification

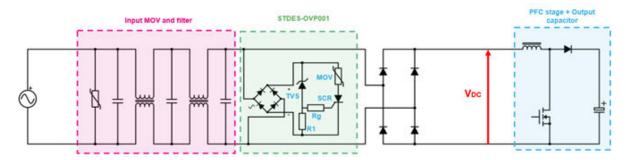


Figure 4. Implementation of the STDES-OVP001 on an SMPS after rectification

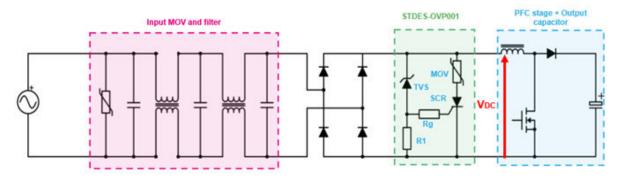


Table 2. STDES-OVP001 versions

Versions	STDES-OVP001V1	STDES-OVP001V2	STDES-OVP001V3	STDES-OVP001V4
Grid voltage	230 V	230 V	230 V	400 V
Surge IEC61000-4-5	±4 kV	±6 kV	±4 kV	±6 kV
Capacitor values	> 250 µF	> 250 µF	50 μF	> 300 µF

DB5116 - Rev 2 page 4/11



4 Performances

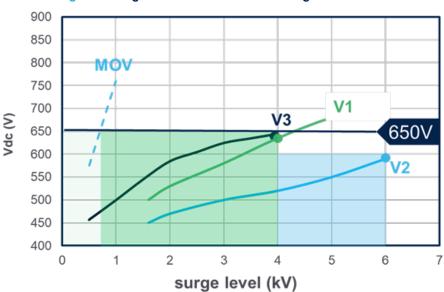


Figure 5. Surge level versus MOSFET voltage for 230 VAC



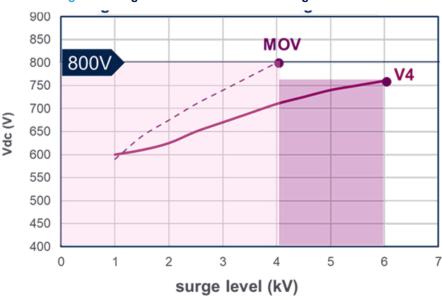


Table 3. Test conditions

Versions	STDES-OVP001V1	STDES-OVP001V2	STDES-OVP001V3	STDES-OVP001V4
Input MOV	S14K385	S14K385	S14K130	S14K175
C _{out} (µF)	270	270	50	300
MOSFET (V _{DSS} in V)	650	650	650	800

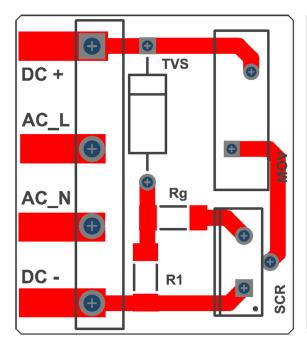
DB5116 - Rev 2 page 5/11





Layout

Figure 7. STDES-OVP001V1 layout



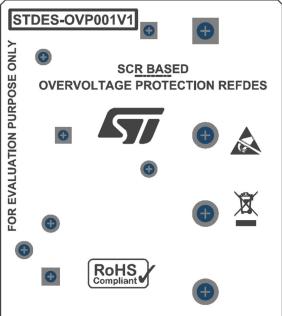
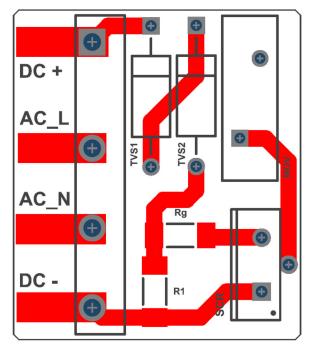
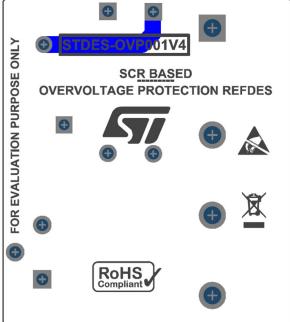


Figure 8. STDES-OVP001V4 layout





DB5116 - Rev 2 page 6/11





PCB stack-up

Figure 9. Layers stack-up

Board Stack Report					
	Stack Up		Layer S	Stack	
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.010mm	3.5
4		Top Layer	Copper	0.070mm	
5		Dielectric 1	FR-4	1.400mm	4.8
6		Bottom Layer	Copper	0.070mm	
7	200 500 500	Bottom Solder	Solder Resist	0.010mm	3.5
8		Bottom Overlay			
9		Bottom Paste			
	Height: 1.560mm				

DB5116 - Rev 2 page 7/11



Standard View

Figure 10. STDES-OVP001V1 standard view

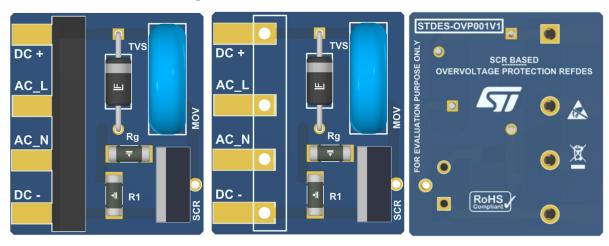
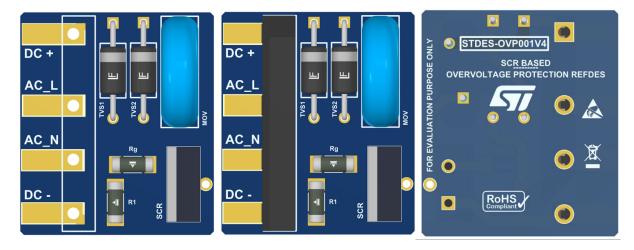


Figure 11. STDES-OVP001V4 standard view



DB5116 - Rev 2 page 8/11



8 3D views

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Figure 12. STDES-OVP001 3D view

DB5116 - Rev 2 page 9/11



Revision history

Table 4. Document revision history

Date	Revision	Changes
04-Oct-2023	1	Initial release.
26-Jul-2024	2	Added Getting started.

DB5116 - Rev 2 page 10/11



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DB5116 - Rev 2 page 11/11